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## \*\* CONTINUING DATA \*\*\*\*\* *yes*

This application is a DIV of 09/797,206 02/27/2001 PAT 6,693,039

## \*\* FOREIGN APPLICATIONS \*\*\*\*\* *yes*

EUROPEAN PATENT OFFICE (EPO) 00830148.3 02/29/2000

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 02/23/2004

Foreign Priority claimed 35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	STATE OR COUNTRY ITALY	SHEETS DRAWING 3	TOTAL CLAIMS 17	INDEPENDENT CLAIMS 3
Verified and Acknowledged <i>9/21/04</i> Examiner's Signature	Initials				

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## TITLE

Process for forming a buried cavity in a semiconductor material wafer and a buried cavity

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